

ABSTRACT

Provided in the present invention is a flipping apparatus, comprising a bracket body, a rotary driver, and a clamping apparatus, a plurality of partition plates being formed on inner side surfaces of two side walls of the bracket body, a carrier slot for the placement of a wafer being formed between each two adjacent partition plates, and rotating shafts being formed on outer side surfaces of the two side walls of the bracket body. The rotary driver is connected to at least one rotating shaft to drive the bracket body to rotate, and the clamping apparatus is disposed on the side wall of the bracket body and is used for pressing or releasing the wafers placed in the carrier slots. In the present invention, by means of the arrangement of the clamping apparatus on the bracket body holding the wafers, the wafers are fixed by the clamping apparatus when the bracket body rotates, effectively avoiding fragments or surface scratches caused by the wafers shaking in the bracket body when the wafers changes posture with the bracket body.